

TQP369184

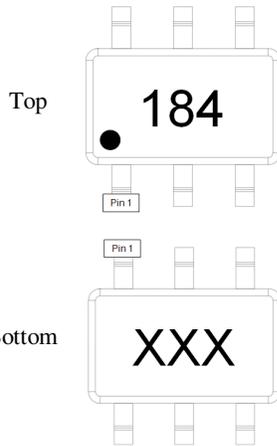
DC-6 GHz Gain Block



Mechanical Information

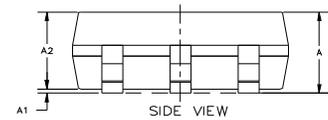
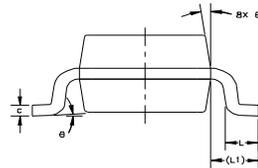
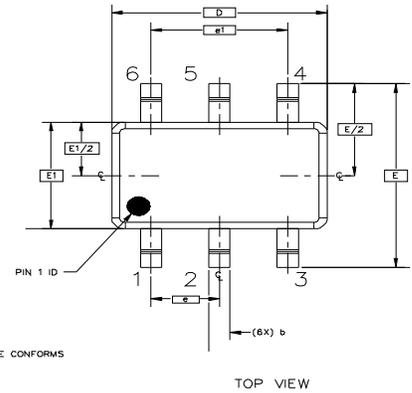
Package Information and Dimensions

The component is marked on the top surface of the package with a "184" designator and on the bottom surface with an alphanumeric lot code.



SYMBOL	MIN	MAX
A	—	1.10 (.043)
A1	0	.10 (.004)
A2	.70 (.028)	1.00 (.039)
D	2.00 (.079)	BASIC
E	2.10 (.083)	BASIC
E1	1.25 (.039)	BASIC
L	.21 (.008)	.41 (.016)
L1	.42 (.017)	REF
L2	.15 (.006)	BASIC
Ø	Ø.8	Ø.8
Ø1	4.8	12.8
b	.30 (.006)	.30 (.012)
c	.08 (.003)	.22 (.009)
e	.55 (.026)	BASIC
e1	1.30 (.051)	BASIC

NOTES:
 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1194. PACKAGE CONFORMS TO JEDEC MO-203, ISSUE B.
 2. DIMENSIONS ARE IN MILLIMETERS (INCHES).



Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.

Notes:

1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
3. RF trace width depends upon the PC board material and construction.
4. Use 1 oz. Copper minimum

Land Pattern

